

DIFFERENTIAL PAIR ARRAY DPAF SERIES

SPECIFICATIONS

For complete specifications see www.samtec.com?DPAF

- Insulator Material:** Black Liquid Crystal Polymer
- Contact Material:** Copper Alloy
- Plating:** Au over 50µ" (1.27µm) Ni
- Current Rating:** Testing Now!
- Operating Temp Range:** -55°C to +125°C
- Contact Resistance:** Testing Now!
- Working Voltage:** Testing Now!
- Mated Cycles:** Testing Now!

Note: Some sizes, styles and options are non-standard, non-returnable.

Mates with:
DPAM

Low Insertion/
Extraction forces



Differential Pairs

Staggered layout reduces grounds required

Performance of up to a terabit per connector

(2,54mm) .100" pitch

(2,16mm) .085" pitch

Perimeter grounds

Solder crimped to tails

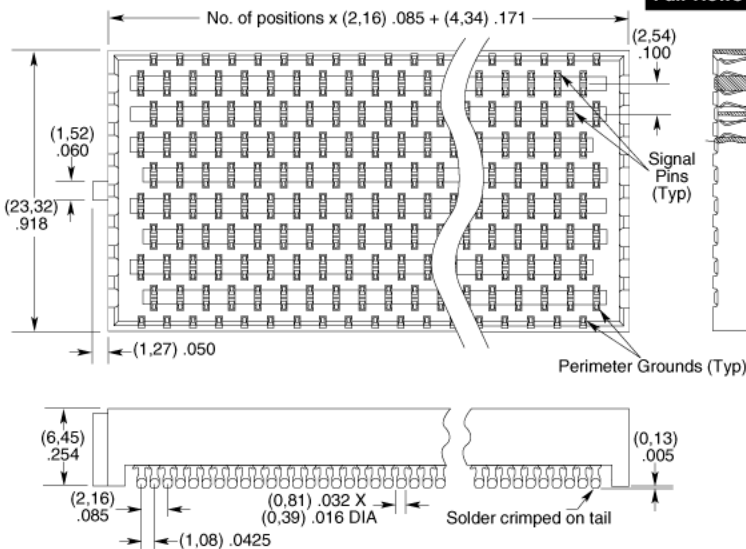
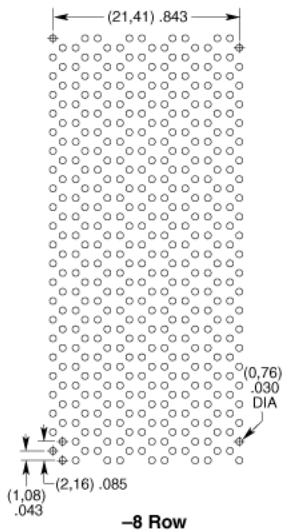
RoHS NOTE

DPAF with Type -1 Solder crimp NOT RoHS Compliant.
DPAF with Type -2 Solder RoHS Compliant.

Processing:

- Max Processing Temp:** 230°C for 60 seconds with Type -1 solder crimp, or 230°C for 60 seconds, or 260°C for 20 seconds 3x with Type -2 solder crimp
- Lead-Free Solderable:** Type -1: No
Type -2: Yes
- Suggested PCB Layouts:** For reference only. Please contact Samtec or go to www.samtec.com?DPAF for recommended PCB layout.

DPAF	PAIRS PER ROW	03.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION
	-08, -15, -23, -30 = (-3 row only)		-H = 30µ" (0,76µm) Gold on contact area, Gold Flash on solder tail	-8 = Eight Pair Rows (N/A in -30) -3 = Three Pair Rows	-1 = 63% Sn/37% Pb Solder Crimp -2 = Lead-Free Tin Alloy Solder Crimp	-K = (20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad -TR = Tape & Reel



SIZE	USABLE PAIRS PER ARRAY*
-08 x -8	48 Pairs
-15 x -8	104 Pairs
-23 x -8	168 Pairs
-08 x -3	18 Pairs
-15 x -3	39 Pairs
-23 x -3	63 Pairs
-30 x -3	84 Pairs

*Assumes first and last pair in each row are grounded

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM